

Amendments to the Specification:

*Please replace the paragraph beginning at page 7, line 4, with the following:*

Figure 4A illustrates a bottom view of the processor module mounting assembly 100. In this embodiment, the processor mounting module 106 includes a daughter card 120 upon which the processor die 109 is mounted. A thermal interface material (TIM) is applied to the microprocessor die 109 for power dissipation. One of ordinary skill in the art recognizes that the processor could be mounted directly on the printed circuit board 104 and the heatsink 110 could be placed directly thereon to provide the same cooling effect. Figure 4B is an illustration of the spring-loaded mount 121 of the mounting module, including securing screws 180, standoff caps, springs, and standoff housings, as shown. Figure 4C illustrates an exploded view of the mounting module.

*Please replace the paragraph beginning at page 8, line 19, with the following:*

Tapered pin features, including fine locator pins 160 and 162 and coarse locator pin 164, are provided to locate the processor mounting module relative to the printed circuit board, allowing blind engagement. The guide feature tolerances are determined so as to prevent inadvertent damage of delicate high density signal connectors during blind insertion.